

Claims

Cancel claims 7, 28-32, 35-36 and 39.

In claim 2, Lines 7^{and}~~9~~, 16 after "substrate," delete "and";

in Lines 8-9 after "substrate;" delete "and" in Line 9

in Line 5 after "in a" insert - - first - -;

in Line 8 after "substrate" insert - -, wherein a width in a second direction of the second portion of the first circuit line exceeds a width in the second direction of the first portion of the first circuit line, wherein the second direction is oriented parallel to the surface of the substrate- -; and

in Line 17 after "contact" insert - -, and wherein a width in the second direction of the second portion of the second circuit line exceeds a width in the second direction of the first portion of the second circuit line;

an electronic assembly coupled to the first conductive pad; and

an electronic carrier coupled to the second conductive pad- -.

Lines 16-17
In claim 3, ~~Line 16~~, after "substrate," delete "and" in line 17; and in Line 23 after "substrate," delete "and";

in Line 12 after "in" delete "a" and insert - - the - -;

in Line 13 after "to" delete "a" and inset - - the - -;

in Line 22 after "in" delete "a" and inert - - the - -;

in Line 22 after "to" delete "a" and inert - - the - -;

In Line 24 after "substrate," insert - -, wherein the third circuit line physically touches the first circuit line in direct surface-to-surface contact, and wherein the third circuit line physically touches the second circuit line in direct surface-to-surface contact;

an electronic assembly coupled to the first conductive pad; and

an electronic carrier coupled to the second conductive pad- -.

In claim 9, Lines 2 and 4 after "ball" delete "coupled to" and insert - - coupling - -, and in Line 2 after "pad" insert - - to the electronic assembly; and - -;

In Line 3, delete "an electronic assembly coupled to the first solder ball;"

In Line 4 after “pad” delete “and an electronic carrier coupled to the second solder ball” and insert - - to the electronic carrier- -;

In claim 12, Line 3, after “coating;” delete ^{“;” and} “an” in Line 4 and insert - - wherein the- -;

in Line 4, after “assembly” insert - - is - - and after “interconnect;” insert - - and- -;

in Line 5, after “pad~~x~~” delete “; and an” and insert - - wherein the - -;

in Line 6, after “carrier” insert - - is - -.

in claim 34, Line 2 after “interconnect” delete “coupled to” and insert - - coupling - -;

In Line 3 after “coating” delete “; an electronic assembly coupled to the wirebond interconnect;” and insert - - to the electronic assembly; and - -;

In Line 5 after “ball” delete “coupled to” and insert - - coupling - -.

In Line 5 after “pad” delete “; and electronic carrier coupled to the solder ball” and insert - - to the electronic carrier - -.